

What is claimed is:

1. A cleaning apparatus to clean alien substance from a substrate provided with a mask pattern prior to wet etching, the apparatus comprising:

an ultraviolet cleaner; and

a conveyer conveying the substrate to and from the ultraviolet cleaner.

2. The apparatus according to claim 1, wherein the conveyer includes:  
a first conveyer conveying the substrate from a loader to the ultraviolet cleaner; and

a second conveyer conveying the substrate from the ultraviolet cleaner to a wet etching unit.

3. The apparatus according to claim 1, wherein the ultraviolet cleaner uses eximer ultraviolet light.

4. The apparatus according to claim 1, wherein the substrate includes at least one of a gate electrode, a source electrode, a drain electrode, a pixel electrode, and a protective layer.

5. The apparatus according to claim 1, wherein the substrate includes at least one of a black matrix and a common electrode.

6. A wet etching apparatus to clean alien substances from a substrate with a mask pattern prior to wet etching, the apparatus comprising:

an ultraviolet cleaner cleaning the alien substances from the substrate;

a conveyer conveying the substrate to and from the ultraviolet cleaner;

a loader loading the substrate to and from the ultraviolet cleaner; and

an etching unit etching the substrate that is free of the alien substances, the conveyer conveying the substrate from the ultraviolet cleaner into the etching unit.

7. The apparatus according to claim 6, wherein the conveyer includes:  
a first conveyer conveying the substrate from the loader to the  
ultraviolet cleaner; and  
a second conveyer conveying the substrate from the ultraviolet cleaner  
to the etching unit.

*Sub 11*  
8. The apparatus according to claim 6, wherein the ultraviolet cleaner  
is installed at a predetermined area in the loader on the substrate having a  
plurality of cassettes.

9. The apparatus according to claim 6, wherein the conveyer is  
installed at a predetermined area between the ultraviolet cleaner and the  
etching unit in the loader.

10. The apparatus according to claim 6, wherein the substrate  
includes at least one of a gate electrode, a source electrode, a drain  
electrode, a pixel electrode, and a protective layer.

11. The apparatus according to claim 6, wherein the substrate  
includes at least one of a black matrix and a common electrode.

12. The apparatus according to claim 6, further comprising:  
a tilt drain part flowing an etchant on the substrate;  
a de-ionized rinse part eliminating the etchant on the substrate; and  
a spin drier drying a de-ionized water.

13. A method to clean alien substances from a substrate with a  
photoresist mask pattern, the method comprising:  
forming the photoresist mask pattern on the substrate;  
conveying the substrate to a clean device;  
exposing the substrate to an ultraviolet light to remove the alien  
substances; and

conveying the substrate from the cleaning device to an etching station.

14. The method according to claim 13, wherein the ultraviolet light includes eximer ultraviolet light.

15. A method for wet etching comprising:  
cleaning a substrate having an alien substances from an ultraviolet cleaner;  
conveying the substrate to and from the ultraviolet cleaner;  
loading the substrate to a loader; and  
etching the substrate in an etching unit.

16. The apparatus according to claim 15, wherein the substrate includes at least one of a gate electrode, a source electrode, a drain electrode, a pixel electrode, and a protective layer.

17. The apparatus according to claim 15, wherein the substrate includes at least one of a black matrix and a common electrode.

Sub 18. The apparatus according to claim 15, further comprising:  
flowing an etchant on the substrate in a tilt drain part;  
eliminating the etchant on the substrate in a de-ionized rinse part having a de-ionized water; and  
drying the de-ionized water in a spin drier.